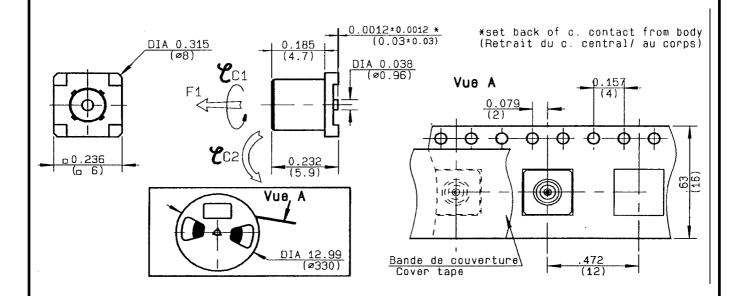
**SMT TYPE - REEL OF 500** 

R113.424.020

Series: MCX



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2

**Issue:** 0412 D



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R113.424.020

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### **PACKAGING**

Standard	Unit	Other
500	-	Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

Impedance  $\mathbf{50} \Omega$  Frequency  $\mathbf{0-6} \text{ GHz}$ 

Frequency **0-6** GHz VSWR **1.05** + **0.050** x F(0)

VSWR 1.05 + 0.050 x F(GHz) Maxi Insertion loss 0.03  $\sqrt{F(GHz)}$  dB Maxi

RF leakage - ( NA - F(GHz)) dB Maxi Voltage rating 335 Veff Maxi

Dielectric withstanding voltage Insulation resistance Insulation  $\Omega$  Insulation resistance Insulation  $\Omega$  Insulation resistance Insulation  $\Omega$  Insulation

#### **ENVIRONMENTAL**

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

#### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

Drawing page 1:

FORCE F1:90N-TORQUES C1:45Ncm-C2:80Ncm

#### **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.600** g

**Issue:** 0412 D



**SMT TYPE - REEL OF 500** 

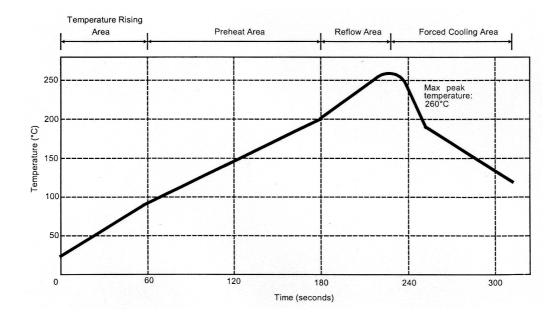
R113.424.020

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#### SOLDER PROCEDURE

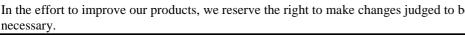
- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microms mini. ( .006 inch mini ). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port (see page 4) centered into body and push against it. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below please find ,the typical profile to use.
- Cleaning of printed circuit boards.
- Verification of solder joints and position of the component by visual inspection.

#### **TEMPERATURE PROFIL**



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

**Issue:** 0412 D

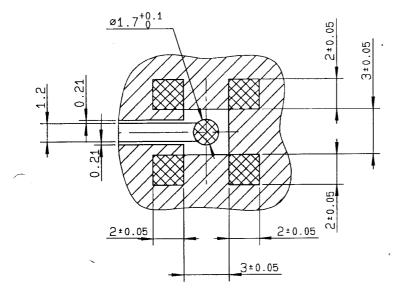


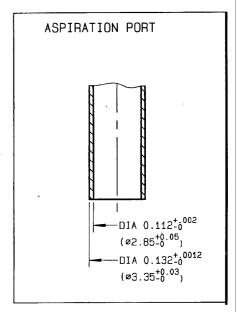


#### **SMT TYPE - REEL OF 500**

R113.424.020

Series: MCX





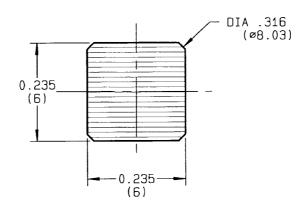
COPLANAR LINE
Pattern and signal are on the same side
Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy resin
of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed
exept for the land pattern on the PCB.

Pattern



Land for solder paste

# SHADOW OF MCX RECEPTACLE FOR VIDEO CAMERA



**Issue:** 0412 D

